

Features

- Surface Mount Package Ideally Suited for Automated Insertion
- Very Low Leakage Current
- **Lead Free By Design/RoHS Compliant (Note 1)**
- **"Green" Device (Note 4 and 5)**

Mechanical Data

- Case: SOT-563
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminal Connections: See Diagram
- Terminals: Finish — Matte Tin annealed over Alloy 42 leadframe. Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 2
- Ordering Information: See Page 2
- Weight: 0.003 grams (approximate)

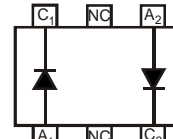


TOP VIEW



BOTTOM VIEW

SOT-563


 TOP VIEW
Internal Schematic

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	85	V
Working Peak Reverse Voltage	V_{RWM}		
DC Blocking Voltage	V_R		
RMS Reverse Voltage	$V_{R(RMS)}$	60	V
Forward Continuous Current (Note 2)	I_{FM}	215	mA
Repetitive Peak Forward Current	I_{FRM}	500	mA
Non-Repetitive Peak Forward Surge Current	I_{FSM}	@ $t = 1.0\mu\text{s}$	4.0
		@ $t = 1.0\text{ms}$	1.0
		@ $t = 1.0\text{s}$	0.5

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 2)	P_D	150	mW
Thermal Resistance Junction to Ambient Air (Note 2)	$R_{\theta JA}$	833	$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-65 to +150	$^\circ\text{C}$

Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 3)	$V_{(BR)R}$	85	—	—	V	$I_R = 100\mu\text{A}$
Forward Voltage	V_{FM}	—	—	0.90	V	$I_F = 1.0\text{mA}$
				1.0		$I_F = 10\text{mA}$
				1.1		$I_F = 50\text{mA}$
				1.25		$I_F = 150\text{mA}$
Leakage Current (Note 3)	I_{RM}	—	—	5.0	nA	$V_R = 75\text{V}$
				80		$V_R = 75\text{V}, T_J = 150^\circ\text{C}$
Total Capacitance	C_T	—	2	—	pF	$V_R = 0, f = 1.0\text{MHz}$
Reverse Recovery Time	t_{rr}	—	—	3.0	μs	$I_F = I_R = 10\text{mA}, I_{rr} = 0.1 \times I_R, R_L = 100\Omega$

- Notes:
1. No purposefully added lead.
 2. Part mounted on FR-4 PC board with recommended pad layout, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
 3. Short duration pulse test used to minimize self-heating effect.
 4. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
 5. Product manufactured with Date Code UO (week 40, 2007) and newer are built with Green Molding Compound. Product manufactured prior to Date Code UO are built with Non-Green Molding Compound and may contain Halogens or Sb_2O_3 Fire Retardants.

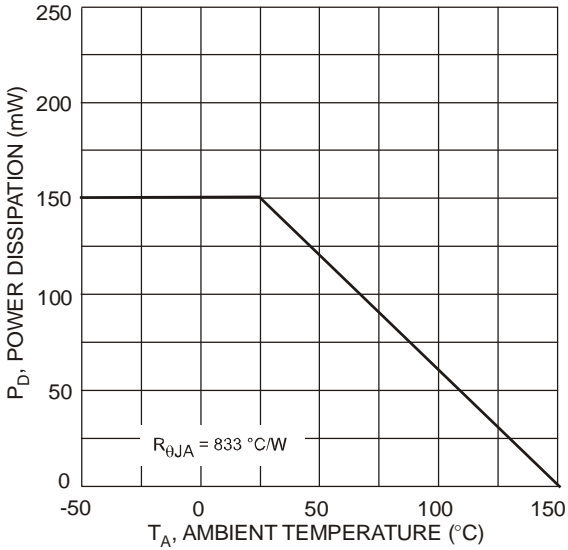


Fig. 1 Power Derating Curve, Total Package

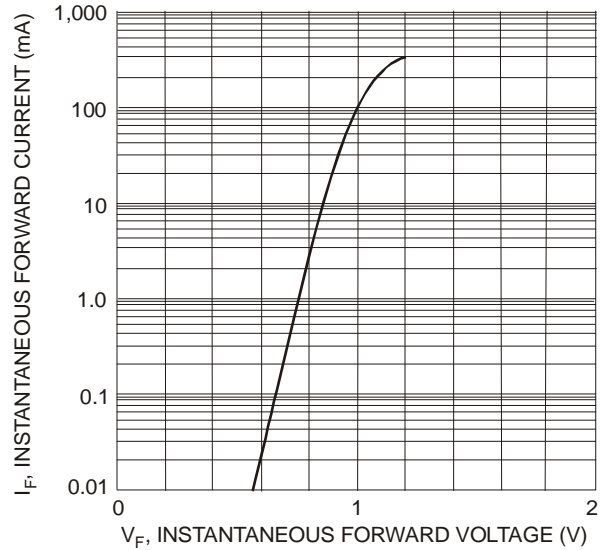


Fig. 2 Typical Forward Characteristics, Per Element

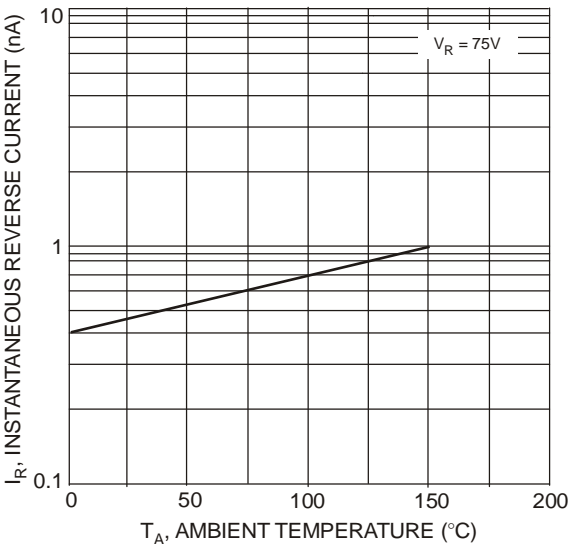


Fig. 3 Typical Reverse Characteristics, Per Element

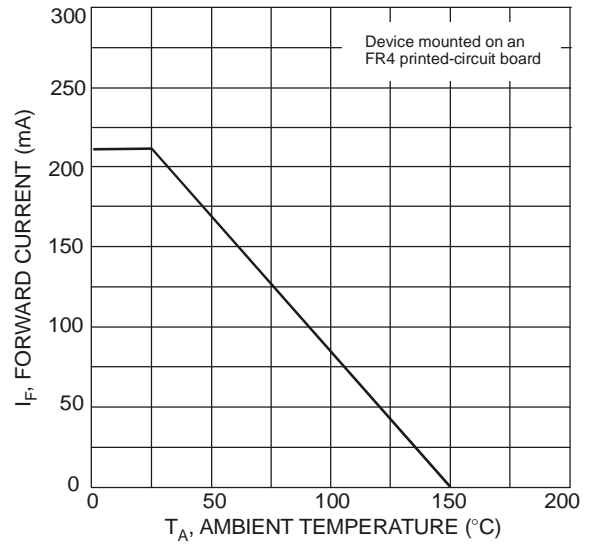


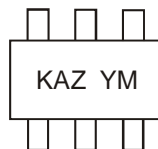
Fig. 4 Current Derating Curve, Per Element

Ordering Information (Note 6)

Part Number	Case	Packaging
BAS116V-7	SOT-563	3000/Tape & Reel

Notes: 6. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information



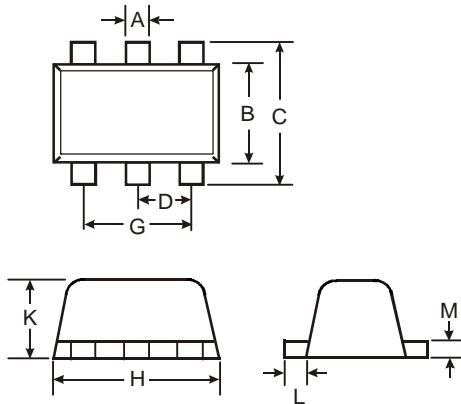
KAZ = Product Type Marking Code
 YM = Date Code Marking
 Y = Year (ex: R = 2004)
 M = Month (ex: 9 = September)

Date Code Key

Year	2004	2005	2006	2007	2008	2009	2010	2011	2012
Code	R	S	T	U	V	W	X	Y	Z

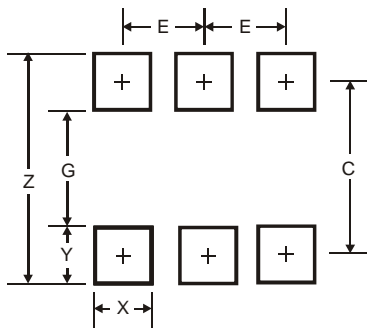
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Package Outline Dimensions



SOT-563			
Dim	Min	Max	Typ
A	0.15	0.30	0.20
B	1.10	1.25	1.20
C	1.55	1.70	1.60
D	0.50		
G	0.90	1.10	1.00
H	1.50	1.70	1.60
K	0.55	0.60	0.60
L	0.10	0.30	0.20
M	0.10	0.18	0.11
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.2
G	1.2
X	0.375
Y	0.5
C	1.7
E	0.5

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Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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